



Cookson Electronics

Assembly Materials

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NEWS RELEASE

Release Immediately

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Cookson Electronics Solar Materials Will Introduce New Products to the North American Market at Solar Power International 2009

South Plainfield, NJ -- July 27, 2009 – Cookson Electronics Solar Materials will participate in Solar Power International 2009, Oct. 27-29, 2009, in Anaheim, CA. Cookson brings its unique mix of metals and chemistry expertise to photovoltaic market applications. Supported by its long term commitment to innovative R&D and close-to-the-customer product technology development, Cookson assists solar cell/panel manufacturers in increasing their cell efficiency and in lowering their cost/watt.

“As a world leader in electronics materials and chemistry, Cookson Electronics offers unique solutions to the photovoltaic industry,” said Bruce Moloznik, Global Vice President – Marketing. “Our new ALPHA® PV Ready Ribbon™ was developed as a result of our intense R&D efforts. PV Ready Ribbon™ increases manufacturing up-time by eliminating the need to apply flux separately during the tabbing and stringing process. It is a proprietary, resilient flux-coated ribbon that is used to link solar cells in the photovoltaic module assembly process. Its unique feature is our patented chemistry and technology used to flux-coat the ribbon.”

The following innovative products will be featured at Solar Power International. They represent Cookson Electronics’ commitment to develop technologies for the rapidly growing solar market.

PV Cell Metallization

Conductive Inks:

ALPHA® n:1000-IJ Silver Conductor Developed to deliver high conductivity for ink jet applications
ALPHA® n:1000-SP Silver Conductor Developed to deliver high conductivity for screen printing applications.

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Stencils:

ALPHA® FORM PV Electroformed Stencils Fine feature printing of metallization lines with higher aspect ratios

Screens:

ALPHA® SCREEN PV For conventional thick film ink printing of metallization lines (USA).

Conductive Adhesives:

POLYSOLDER SE3001 conductive adhesive is a lead-free, silver-filled epoxy with excellent rheological properties for microdot dispensing and screen printing. It is ideal for metallization and assembly applications and will form conductive interconnection or trace at temperatures as low as 130 degrees C.

Plating Chemistry:

ENTHONE® HELIOFAB™ DPC Direct electrolytic copper plating onto conventional silver paste

ENTHONE® HELIOFAB™ ELSP Direct electro-less nickel and copper plating on silicon

PV Module Assembly

Flux-coated Ribbon:

ALPHA® PV-READY RIBBON™ is flux-coated and has demonstrated the ability to eliminate fluxing operations, including maintenance, labor and equipment. It offers superior bond strength and increased up time resulting in production of more panels per day.

Preforms:

ALPHA® PV-READY Exactalloy® Preforms are flux-coated solder/copper shapes that integrate the exact solder volume and flux activity for automated assembly of PV cell back-side interconnects; virtually eliminates VOC emissions.

Flux:

ALPHA® PV-32 Flux Rosin-containing, high reliability, Pb-Free/Sn-Pb capable tabbing and stringing flux

ALPHA® PV-61 Flux Low solids, high reliability, Pb-Free/Sn-Pb capable tabbing and stringing flux

ALPHA® PV-80 Flux Low rosin, Pb-Free/Sn-Pb capable tabbing and stringing flux

ALPHA® PV-21 Flux Water-based, tin-lead and lead-free compatible tabbing and stringing flux allowing for the elimination of VOC emissions.

Solder Paste:

ALPHA® PV-100 Solder Paste No-clean, dispensable, Sn-Pb

ALPHA® PV-200 Solder Paste No-clean, dispensable, Pb-Free, halogen and halide-free

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ALPHA® PV-300 Solder Paste No-clean, dispensable, Pb-Free, wide process window

More information, go to:

<http://alpha.cooksonelectronics.com/products/photovoltaic/photovoltaic-solar-products.asp>

About Cookson Electronics Assembly Materials

Cookson Electronics Assembly Materials, a Cookson Electronics company, is the global leader in the development, manufacturing and sales of innovative materials used in electronic assembly processes. With a unique worldwide presence in 50 locations throughout the Americas, Europe and the Asia/Pacific region, CEAM supplies a full line of Solder Paste, Stencils, Squeegee Blades, Stencil & PCB Cleaners, Bar Solder, Cored Wire Solder, Wave Soldering

Fluxes, and SMD Adhesives. Cookson Electronics Semiconductor Packaging is the leader in EMC and polymeric materials for semiconductor packaging.

Cookson also offers product technologies for the Photovoltaic market to help lower production costs and increase throughput and yield. Since its founding in 1872, Cookson Electronics has been committed to developing and manufacturing the highest quality soldering materials. That tradition continues today through its innovative products, including its line of environmentally friendly, lead-free electronic assembly products. For more information, visit www.cooksonelectronics.com.

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